

UM10945

NTAG I²C *plus* Explorer Kit - Program and Debug Start-up

Rev. 2.2 — 10 October 2022

User manual

Document information

Information	Content
Keywords	NTAG I2C <i>plus</i> , Explorer Kit, Android, NFC tag, OM5569/NT322
Abstract	This user manual aims at describing the procedure how to flash firmware to OM5569/NT322E/ER Connected Tags Explorer Board and use Android application to check successful flashing.



Revision history

Revision history

Rev	Date	Description
2.2	20221010	<ul style="list-style-type: none">• Section 6 "Radio Equipment Directive (RED)" added• Section "Legal information" updated
2.1	20180619	Change from LPCXpresso to MCUXpresso
2.0	20170206	Completely reworked version
1.0	20160216	First version

1 Object

NTAG I²C *plus* Explorer kit is an all-in-one demonstration and development resource to demonstrate the unique properties of the NTAG I²C *plus* tag chip. By including a full complement of hardware and software tools, users cannot only investigate the capabilities of the chip through the various demonstrations, but also develop and test their own applications (additional LPC-Link2 debug probe¹ is required).

This User Manual explains how to upload new firmware using LPCLink2 to “Connected Tags Explorer Boards” Rev 2.0 (and up) and older version Rev G.

Technical aspects related to the IC functioning are beyond the scope of this document. In order to get further technical details please consult the dedicated Datasheet “NTAG I²C *plus*, NFC Forum Type 2 Tag compliant IC with I²C interface” (refer to [Section 7](#)).

The MCUXpresso IDE is the first NXP tools release with combined support for the NXP Kinetis and LPC parts.

MCUXpresso IDE is based on the Eclipse IDE and includes the industry standard Arm GNU toolchain. It brings developers an easy-to-use and unlimited code size development environment for NXP MCUs based on Cortex-M cores (LPC and Kinetis). This new IDE combines the best of the widely popular LPCXpresso and Kinetis Design Studio IDEs, providing a common platform for all NXP Cortex-M microcontrollers. With full-featured free (code size unlimited) and affordable professional editions, MCUXpresso IDE provides an intuitive and powerful interface with profiling, power measurement on supported boards, GNU tool integration and library, multicore capable debugger, trace functionality and more. MCUXpresso IDE debug connections support Freedom, Tower[®], LPCXpresso and your custom development boards with industry- leading open-source and commercial debug probes including LPC-Link2, P&E and SEGGER.

¹ www.nxp.com/LPC-LINK2

2 Download and install latest MCUXpresso IDE

Download latest version from [MCUXpresso IDE Homepage](#).

In this user manual all screenshots are taken from version v10.2.0_759.

Installation guide and user manual may be downloaded from that page.

There is no activation process required for the use of MCUXpresso IDE, all features are available after installation.

3 Importing source files

As a first step, download of latest [firmware source files](#) from [NXP Explorer kit internet pages](#) is recommended.

3.1 Create new workspace for new template.

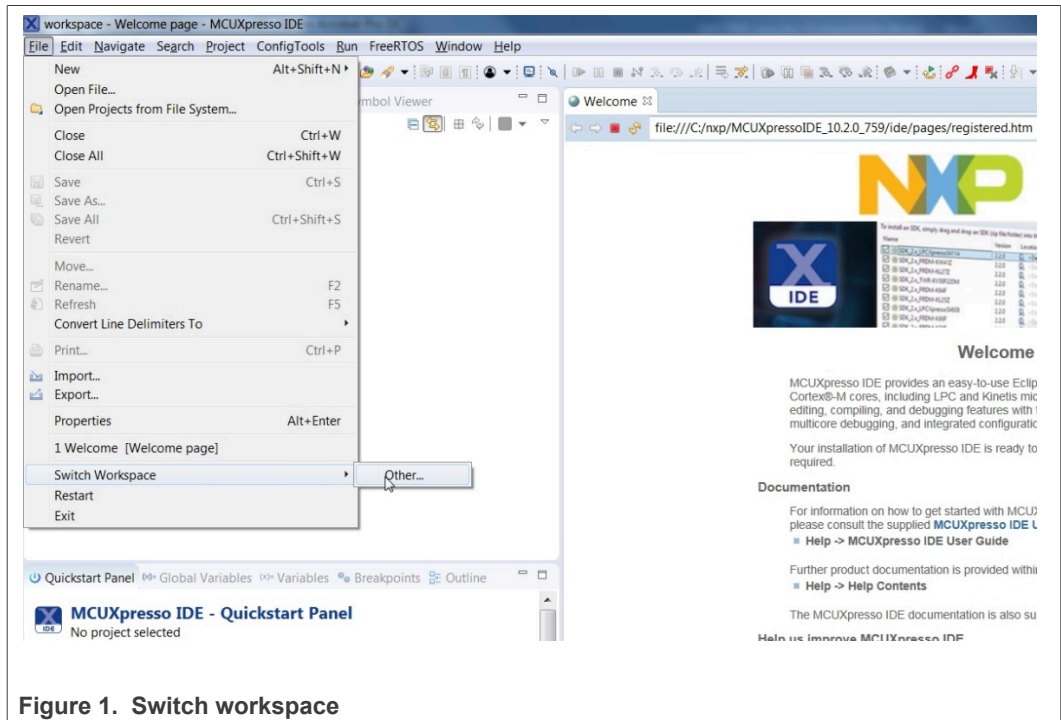


Figure 1. Switch workspace

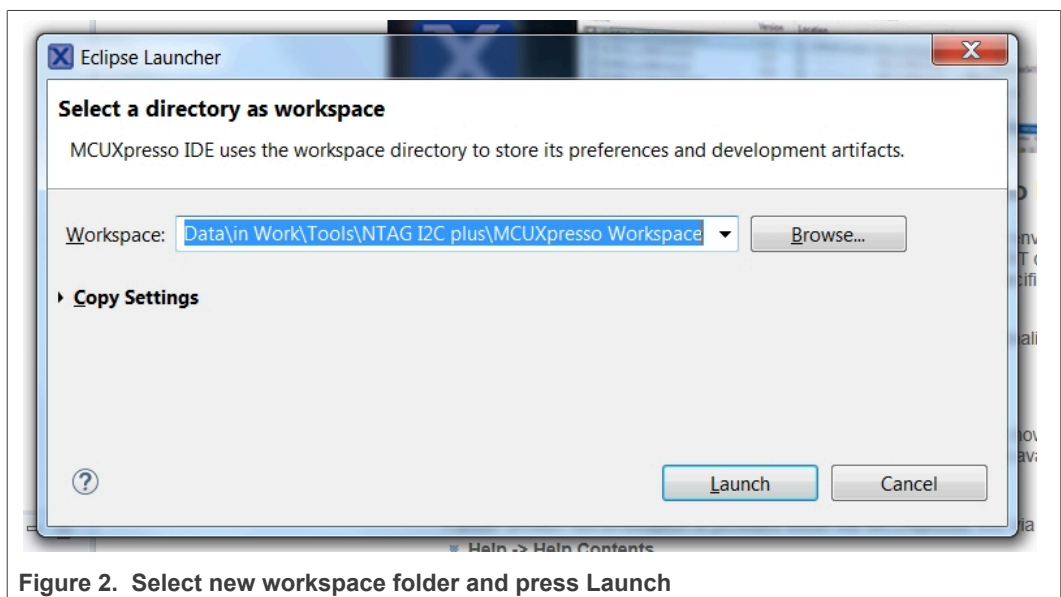


Figure 2. Select new workspace folder and press Launch

3.2 Import project

Select “File/Import”, then “General/Existing Project into Workspace”.

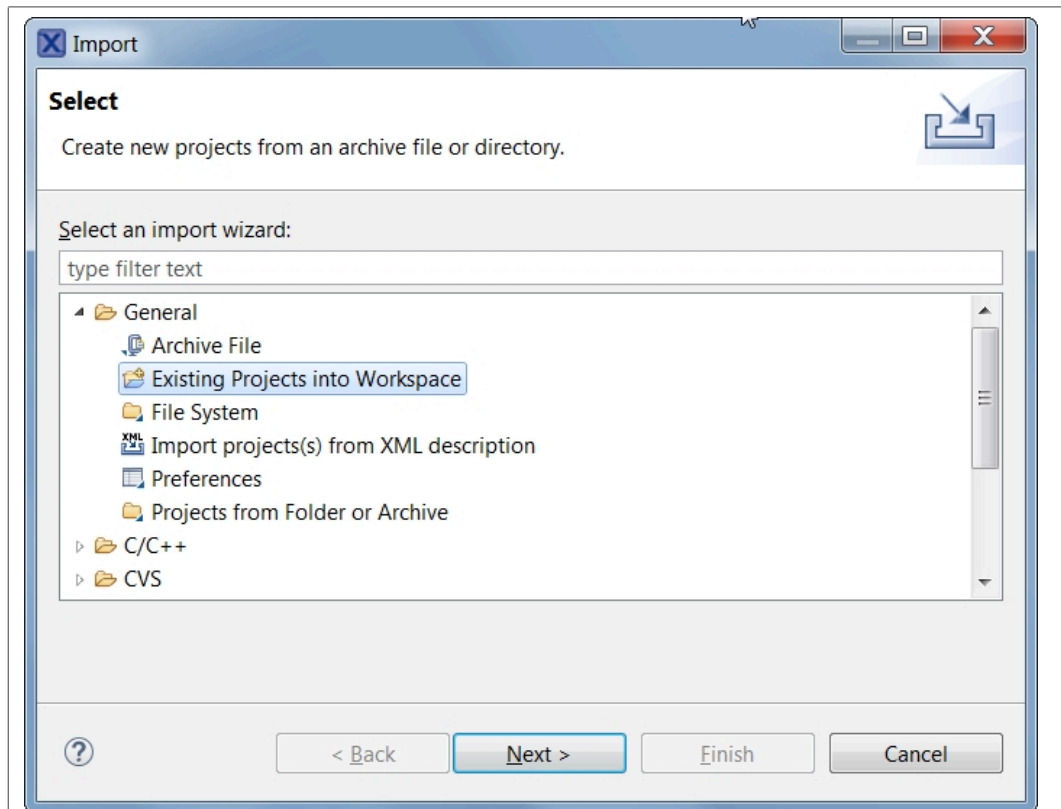


Figure 3. Insert Existing Project into Workspace

Click on “Browse” to the right of “Select Archive File” and select the Project .zip file.

Click “Finish”, six (6) projects are now imported.

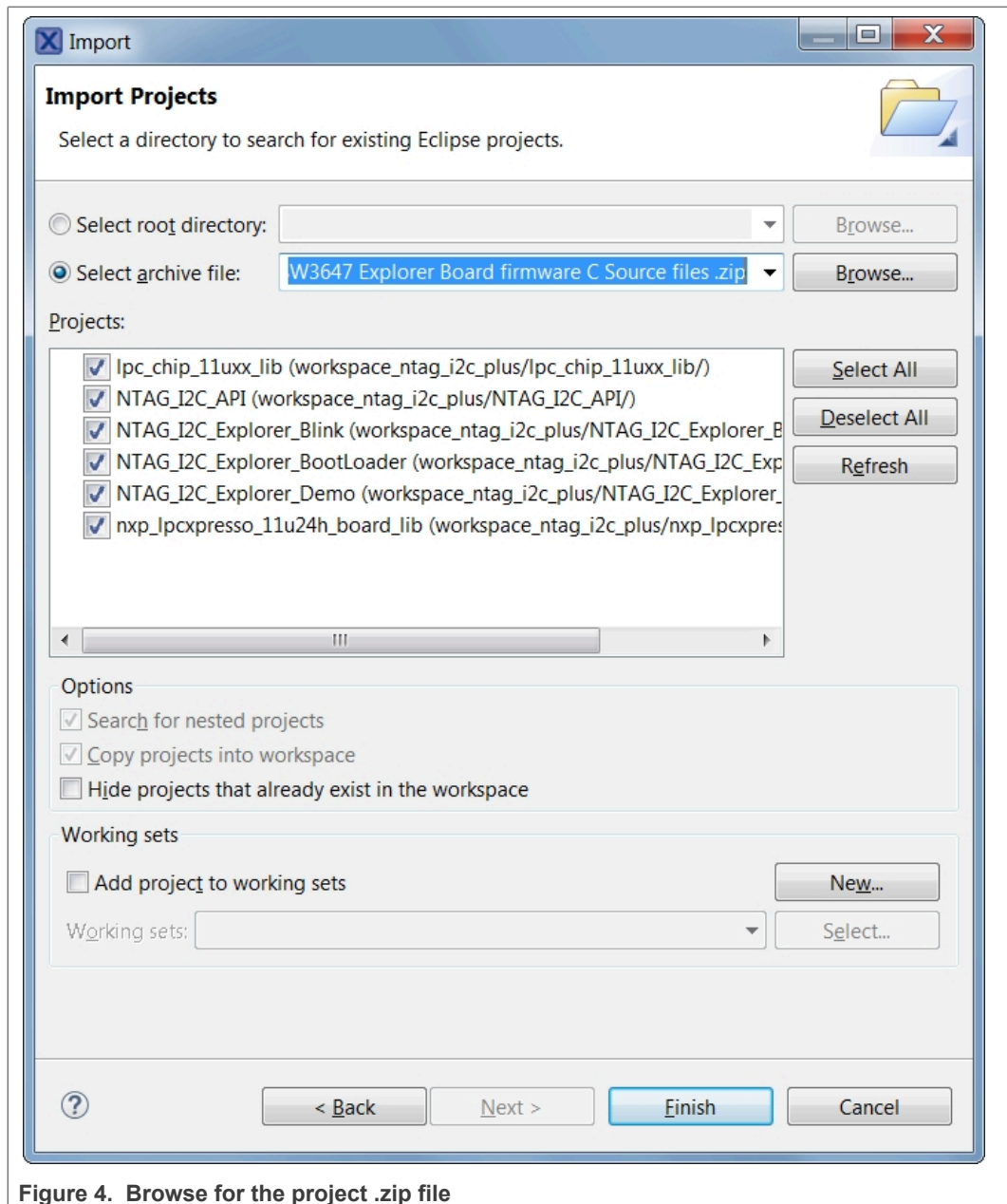


Figure 4. Browse for the project .zip file

4 Programming (flashing) explorer board

1. Connect the LPCLink2 with the Explorer Board using the **10-pin flat cable**
2. Place the **JP2 Jumper** as shown on the picture to power Explorer Board from LPCLink2
3. Connect the LPCLink2 to your computer via **USB** while **pressing ISP button** on Explorer Board

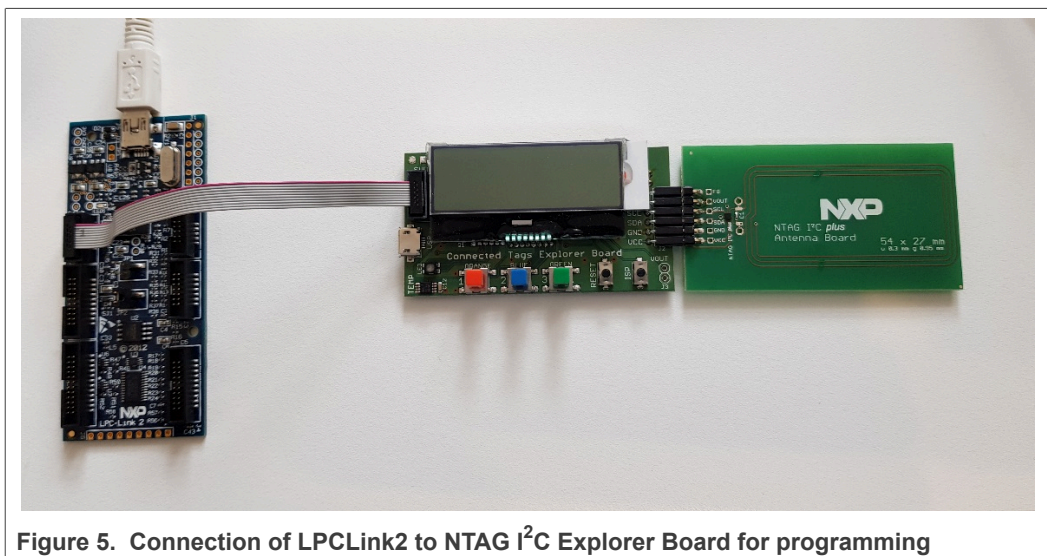


Figure 5. Connection of LPCLink2 to NTAG I²C Explorer Board for programming

4.1 NTAG I²C *plus* Explorer board firmware structure

As described in [Section 7], the firmware which runs on the NTAG I²C *plus* Explorer board, is flashed during the production of the board and supports the demonstration functionality of the hardware. The delivered NTAG I²C *plus* Explorer board firmware consists of three applications:

- **NTAG_I2C_Explorer_Bootloader:** This project implements the secondary bootloader application. It is flashed at on-chip memory address starting at 0x0000 0000 and it is the first application to be executed after the MCU boots. This application has three functions:
 - Jump to the start memory of the user application.
 - Enter into “flashing mode” functionality.
 - Enter into “USB mode” (Peek and Poke).
- **NTAG_I2C_Explorer_Demo:** This project implements the logic supporting the Android / Windows demonstration applications. It is flashed at on-chip flash memory starting at 0x0000 4000 address and it is executed after the bootloader jumps to the application start address.
- **NTAG_I2C_Explorer_Blink:** This is a sample project that sets into blinking mode the NTAG_I2C Explorer board as soon as the RF field is detected. It is flashed at on-chip flash memory starting at 0x0000 4000 address and it is executed after the bootloader jumps to the application start address. This application is provided to illustrate the NFC flashing functionality and its binary image is provided embedded by default into the Android app (see Section 4.5 in [UM10966]).

4.2 Flash BOOTLOADER

Select the Project “NTAG_I2C_Explorer_Bootloader” (1) and click on “Program Flash” (2).

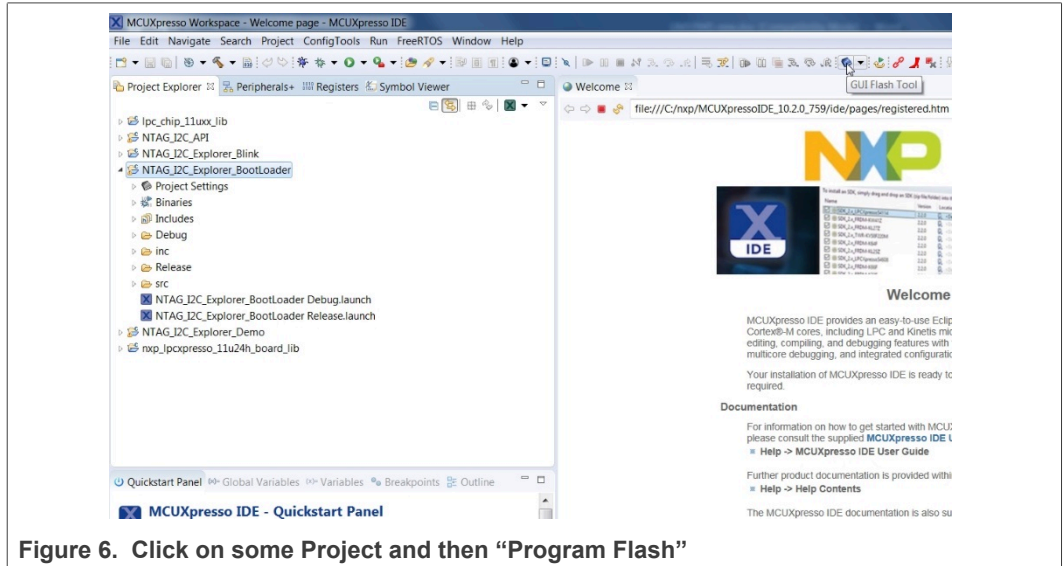


Figure 6. Click on some Project and then “Program Flash”

Check if the right target is selected LPC11xx (NXP LPC11U24/401) as shown on [Figure 7](#). If not, please see [Section 5](#) section.

Click “Workspace...” and search for latest built binary file (.axf). File is located in workspace folder you created in step [Section 3.1](#) (Fig 2), in “Release” folder. Press “OK”.

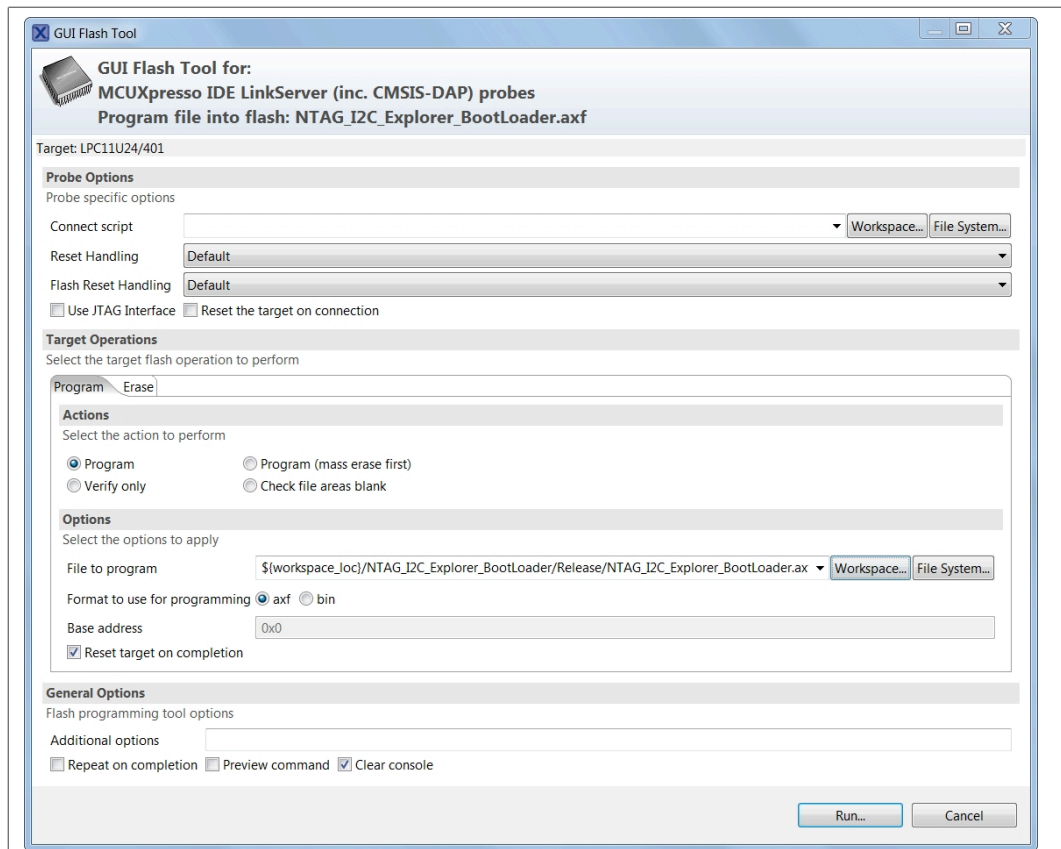


Figure 7. Program Flashing pop-up window

Flashing should start. In case of issues please see [Section 5](#) section .

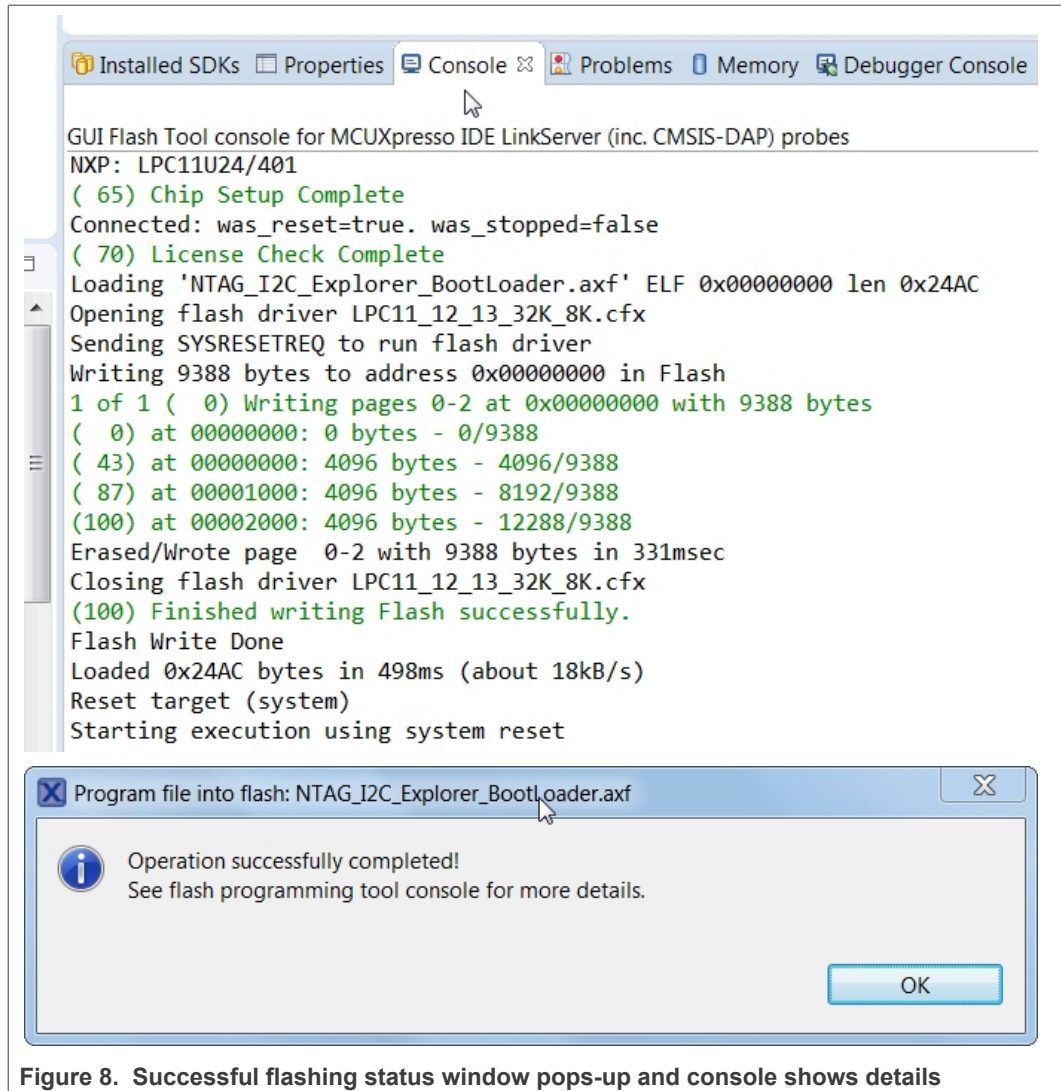


Figure 8. Successful flashing status window pops-up and console shows details

4.3 Flash DEMO APPLICATION

Flashing DEMO APP can be done in two ways:

1. Using LPCLink2 and LPCXpresso, the same way as “Flash BOOTLOADER” was flashed. Described in [Section 4.2](#).
2. Since “NTAG_I2C_Explorer_Bootloader” firmware enables functionality of flashing MCU firmware via NFC enabled cell phone, this step can be taken. Using Android app (NTAG I²C Demo 1.7.6). Detailed procedure is described on page 32 of [\[Section 7\]](#) - user manual NTAG I²C demo app.

4.4 Test flashed firmware



Figure 9. Explorer Board working

5 Troubleshoot

5.1 No compatible emulators found

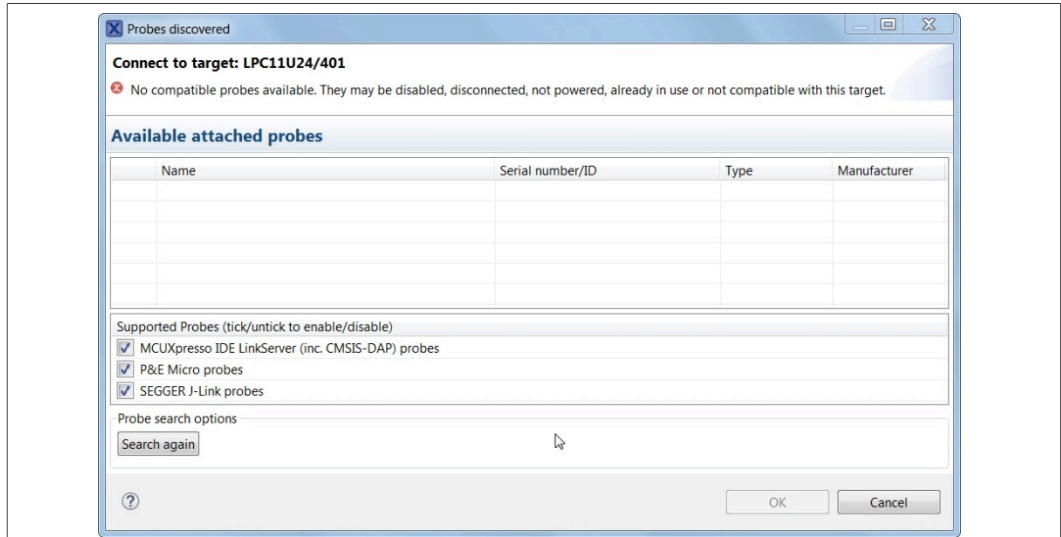


Figure 10. No compatible emulators found

- Check JP2 jumper
- Reconnect the LPCLink2 USB to PC

5.2 Could not connect to core

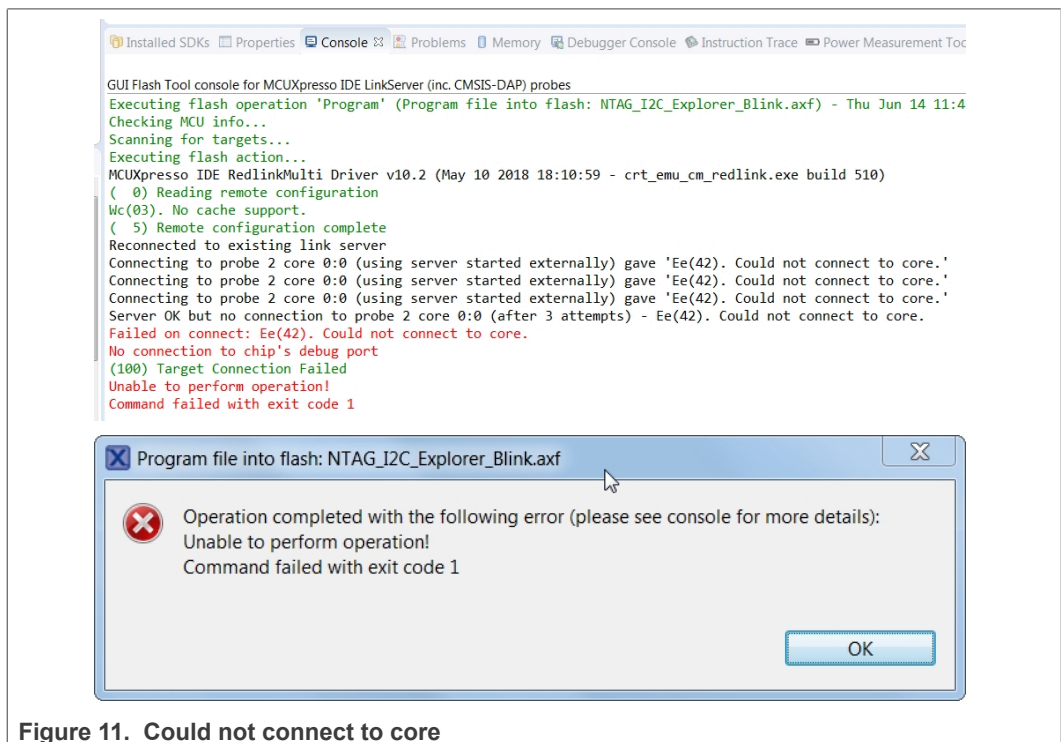


Figure 11. Could not connect to core

- Check your flat cable connection. Flat cables may run out quickly if not handled appropriately.
- Restart redlinksrv.exe service running in Task Manager
- MCU cannot enter DFU mode. Disconnect Explorer Kit board from LPCLink2 (or external power), press and hold ISP button on Explorer Kit board, connect the Explorer Kit board to LPCLink2 (or external power). Try to flash.

5.3 Wire ACK Fault in DAP access

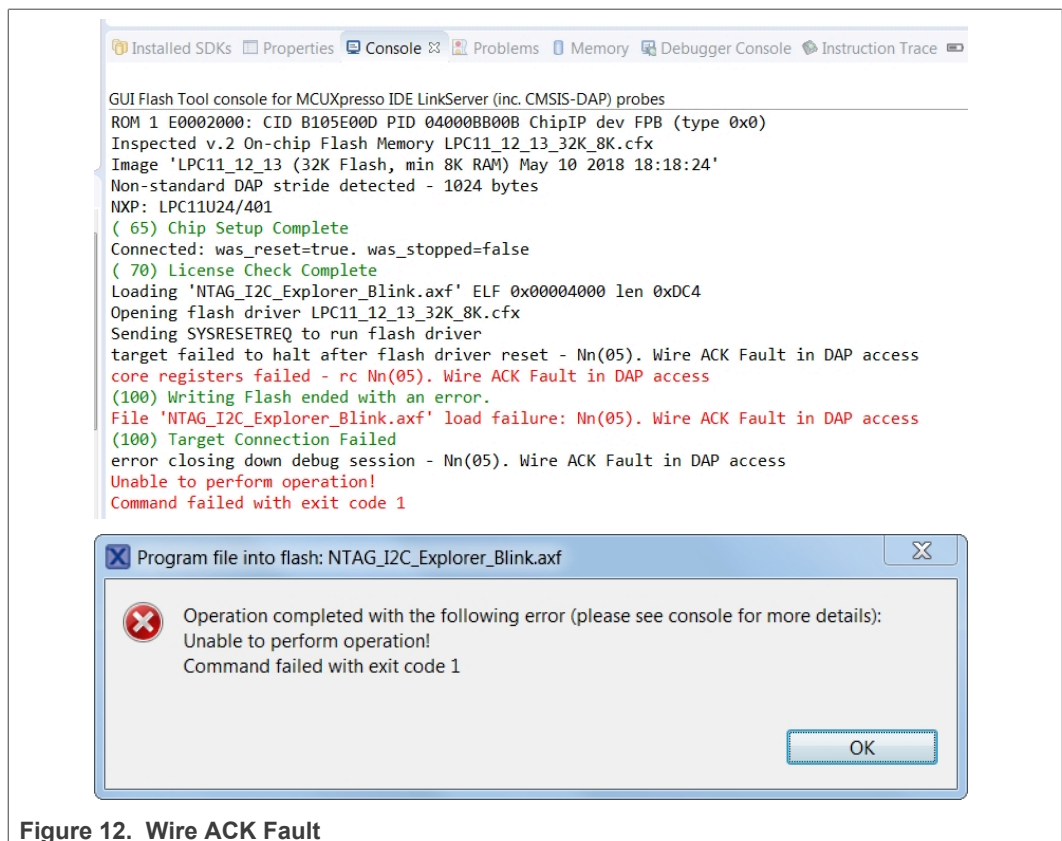


Figure 12. Wire ACK Fault

- Reconnect Explorer Kit via flat cable or LPCLink board via USB cable while pressing ISP button on Explorer Kit.

5.4 Firmware size is too big

```

c:/nxp/lpcxpresso_7.9.0_455/lpcxpresso/tools/bin/./lib/gcc/arm-none-eabi/4.9.3/././././././././arm-none-eabi/bin/ld.exe: NTAG_I2C_Explorer_Demo.axf section `.text' will not fit in region `MFlash32'c:/nxp/lpcxpresso_7.9.0_455/lpcxpresso/tools/bin/./lib/gcc/arm-none-eabi/4.9.3/././././././././arm-none-eabi/bin/ld.exe: region `MFlash32' overflowed by 200 bytescollect2.exe: error: ld returned 1 exit statusmake: *** [NTAG_I2C_Explorer_Demo.axf] Error 1
  
```

Figure 13. Firmware size is too big.

- Right click Project you are trying to flash. Left click "Properties". Under "C/C++ Build" – "Settings", in the tab "Tool Settings" – "Optimization, set "Optimization Level" to "Optimize (-O0)".

Re-build sources and flash again.

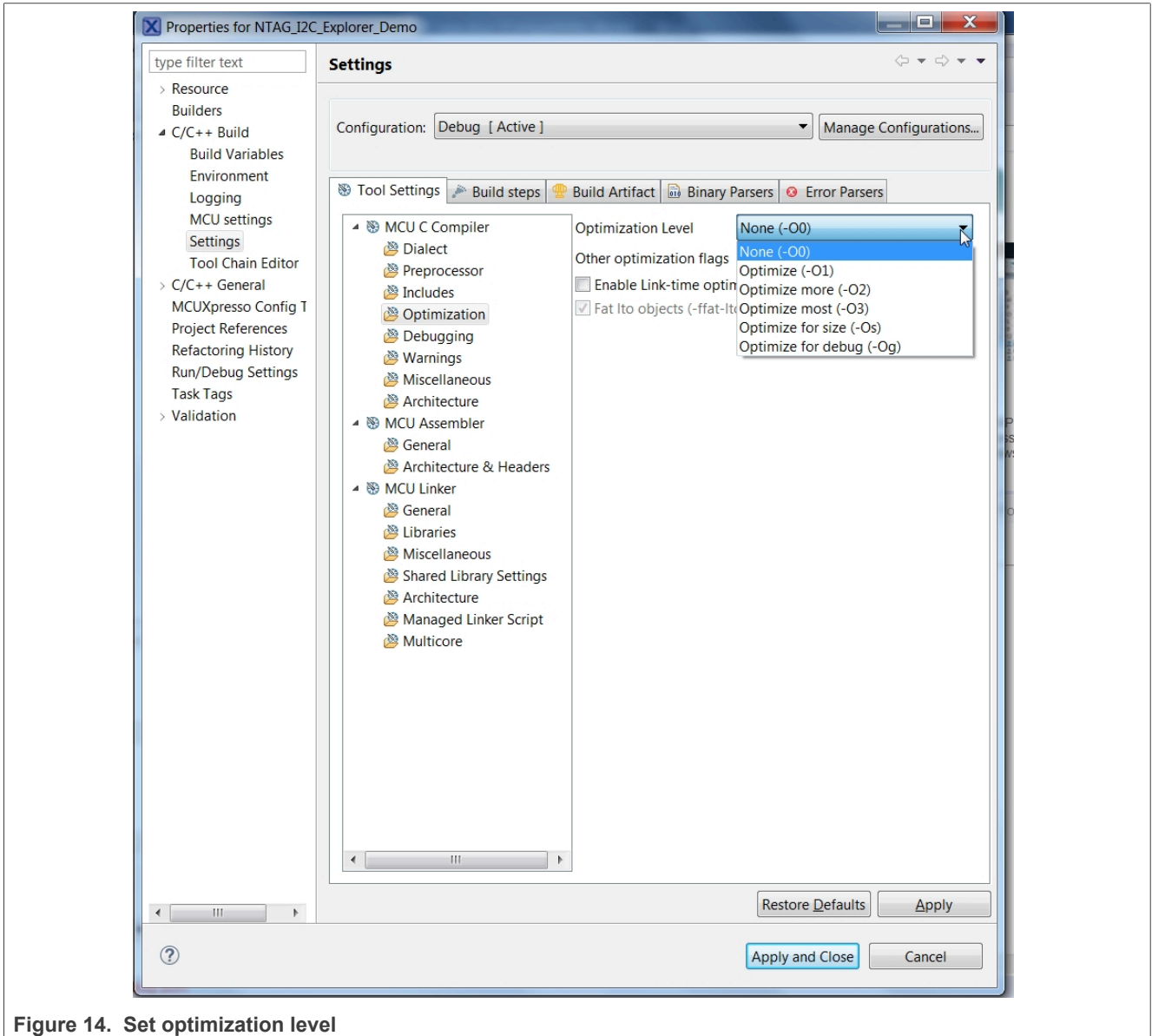


Figure 14. Set optimization level

6 Radio Equipment Directive (RED)

The following information is provided per Article 10.8 of the Radio Equipment Directive 2014/53/EU:

- (a) Frequency bands in which the equipment operates.
- (b) The maximum RF power transmitted.

Table 1. Characteristics

PN	RF Technology	(a) Freq Ranges (EU)	(b) Max Transmitted Power
OM5569-NT322E	Near Field Communication	13.56 – 13.56 MHz	0 dB

EUROPEAN DECLARATION OF CONFORMITY (Simplified DoC per Article 10.9 of the Radio Equipment Directive 2014/53/EU). This apparatus, namely OM5569-NT322E, conforms to the Radio Equipment Directive 2014/53/EU. The full EU Declaration of Conformity for this apparatus can be found at this location: [NTAG I²C *plus* Explorer Kit](#) under "Reliability and Quality Information".

7 References

[NTAGI²C *plus*] NT3H2111/NT3H2211, NTAG I²C *plus*, NFC Forum T2T with I²C interface, password protection and energy harvesting https://www.nxp.com/docs/en/data-sheet/NT3H2111_2211.pdf

[UM10966] NTAG I²C *plus* Explorer Kit - Android Demo <https://www.nxp.com/docs/en/user-guide/UM10966.pdf>

[DEMOBOARD] demo board homepage with all resources www.nxp.com/demoboard/OM5569

8 Legal information

8.1 Definitions

Draft — A draft status on a document indicates that the content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included in a draft version of a document and shall have no liability for the consequences of use of such information.

8.2 Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors and its suppliers accept no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

Terms and conditions of commercial sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Suitability for use in non-automotive qualified products — Unless this data sheet expressly states that this specific NXP Semiconductors product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NXP Semiconductors accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without NXP Semiconductors' warranty of the product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond NXP Semiconductors' specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NXP Semiconductors for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NXP Semiconductors' standard warranty and NXP Semiconductors' product specifications.

Translations — A non-English (translated) version of a document, including the legal information in that document, is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

Security — Customer understands that all NXP products may be subject to unidentified vulnerabilities or may support established security standards or specifications with known limitations. Customer is responsible for the design and operation of its applications and products throughout their lifecycles to reduce the effect of these vulnerabilities on customer's applications and products. Customer's responsibility also extends to other open and/or proprietary technologies supported by NXP products for use in customer's applications. NXP accepts no liability for any vulnerability. Customer should regularly check security updates from NXP and follow up appropriately. Customer shall select products with security features that best meet rules, regulations, and standards of the intended application and make the ultimate design decisions regarding its products and is solely responsible for compliance with all legal, regulatory, and security related requirements concerning its products, regardless of any information or support that may be provided by NXP.

NXP has a Product Security Incident Response Team (PSIRT) (reachable at PSIRT@nxp.com) that manages the investigation, reporting, and solution release to security vulnerabilities of NXP products.

8.3 Licenses

Purchase of NXP ICs with NFC technology — Purchase of an NXP Semiconductors IC that complies with one of the Near Field Communication (NFC) standards ISO/IEC 18092 and ISO/IEC 21481 does not convey an implied license under any patent right infringed by implementation of any of those standards. Purchase of NXP Semiconductors IC does not include a license to any NXP patent (or other IP right) covering combinations of those products with other products, whether hardware or software.

8.4 Trademarks

Notice: All referenced brands, product names, service names, and trademarks are the property of their respective owners.

NXP — wordmark and logo are trademarks of NXP B.V.

AMBA, Arm, Arm7, Arm7TDMI, Arm9, Arm11, Artisan, big.LITTLE, Cordio, CoreLink, CoreSight, Cortex, DesignStart, DynamIQ, Jazelle, Keil, Mali, Mbed, Mbed Enabled, NEON, POP, RealView, SecurCore, Socrates, Thumb, TrustZone, ULINK, ULINK2, ULINK-ME, ULINK-PLUS, ULINKpro, μ Vision, Versatile — are trademarks or registered trademarks of Arm Limited (or its subsidiaries) in the US and/or elsewhere. The related technology may be protected by any or all of patents, copyrights, designs and trade secrets. All rights reserved.

I2C-bus — logo is a trademark of NXP B.V.

Kinetis — is a trademark of NXP B.V.

NTAG — is a trademark of NXP B.V.

Tables

Tab. 1. Characteristics 16

Figures

Fig. 1.	Switch workspace	5	Fig. 7.	Program Flashing pop-up window	10
Fig. 2.	Select new workspace folder and press Launch	5	Fig. 8.	Successful flashing status window pops-up and console shows details	11
Fig. 3.	Insert Existing Project into Workspace	6	Fig. 9.	Explorer Board working	12
Fig. 4.	Browse for the project .zip file	7	Fig. 10.	No compatible emulators found	13
Fig. 5.	Connection of LPCLink2 to NTAG I2C Explorer Board for programming	8	Fig. 11.	Could not connect to core	13
Fig. 6.	Click on some Project and then "Program Flash"	9	Fig. 12.	Wire ACK Fault	14
			Fig. 13.	Firmware size is too big.	14
			Fig. 14.	Set optimization level	15

Contents

1	Object	3
2	Download and install latest MCUXpresso IDE	4
3	Importing source files	5
3.1	Create new workspace for new template.	5
3.2	Import project	6
4	Programming (flashing) explorer board	8
4.1	NTAG I ² C plus Explorer board firmware structure	8
4.2	Flash BOOTLOADER	9
4.3	Flash DEMO APPLICATION	11
4.4	Test flashed firmware	12
5	Troubleshoot	13
5.1	No compatible emulators found	13
5.2	Could not connect to core	13
5.3	Wire ACK Fault in DAP access	14
5.4	Firmware size is too big	14
6	Radio Equipment Directive (RED)	16
7	References	17
8	Legal information	18

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.
